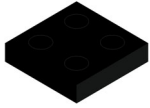
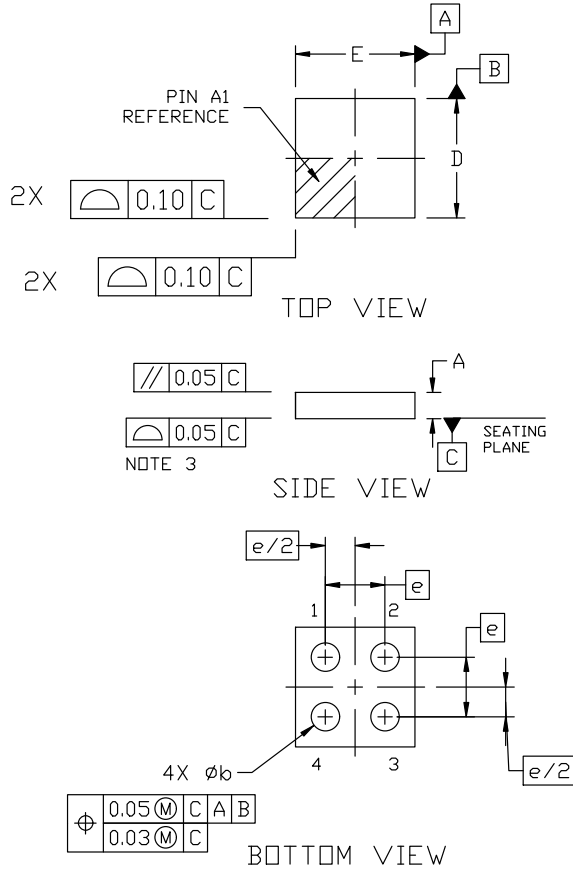


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



**CSP4, 1.01x1.01**  
CASE 568AK  
ISSUE A

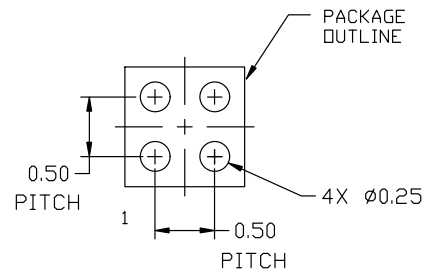
DATE 11 JUL 2022



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	---	---	0.22
b	0.22	0.24	0.26
D	0.99	1.01	1.11
E	0.99	1.01	1.11
e	0.5 BSC		



**RECOMMENDED MOUNTING FOOTPRINT\***

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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